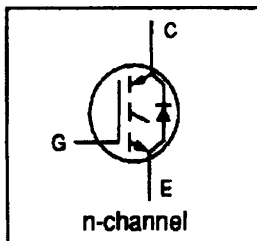


INSULATED GATE BIPOLAR TRANSISTOR WITH ON-BOARD REVERSE DIODE

Ultra Fast-Speed IGBT

- Electrically Isolated
- Hermetically Sealed
- Simple Drive Requirements
- Latch-proof
- UltraFast operation > 10 kHz
- Switching-loss rating includes all "tail" losses
- Ceramic Eyelets



$$V_{CES} = 600V$$

$$f_{ic/2} \approx 20kHz$$

$$I_C @ f_{ic/2} = 18A$$

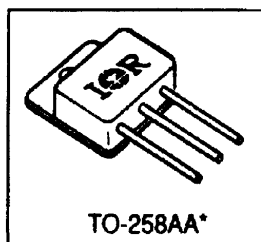
$$V_{CE(sat)} \leq 3.0V$$

$$@ V_{GE} = 15V, I_C = 27A$$

Description

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher usable current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of higher-voltage, higher-current applications.

The performance of various IGBTs varies greatly with frequency. Note that IR now provides the designer with a speed benchmark ($f_{ic/2}$, or the "half-current frequency"), as well as an indication of the current handling capability of the device.



TO-258AA*

*For mechanical specifications
see page G-122

Absolute Maximum Ratings

	Parameter	Max.	Units
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	45*	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	27	
I_{CM}	Pulsed Collector Current ①	220	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
I_{LM}	Clamped Inductive Load Current ②	180	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	200	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	80	W
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ C$
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Weight	10.5	g

* I_C current limited by pin diameter

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case-IGBT	—	—	0.625	$^\circ C/W$
$R_{\theta JC}$	Junction-to-Case-Diode	—	—	1.0	
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.21	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	30	

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{GE} = 0V, I_C = 1.0\text{ mA}$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.60	—	$V/^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0\text{ mA}$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	—	3.0	V	$V_{GE} = 15V, I_C = 27A$
		—	—	3.25		$V_{GE} = 15V, I_C = 45A$
		—	—	2.85		$V_{GE} = 15V, I_C = 27A, T_J = 125^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	5.5	V	$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temp. Coeff. of Threshold Voltage	—	-13	—	$mV/^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ③	16	—	—	S	$V_{CE} = 100V, I_C = 27A, V_{DS} \geq 15V$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{GE} = 0V, V_{CE} = 480V, T_J = 25^\circ\text{C}$
		—	—	5000		$V_{GE} = 0V, V_{CE} = 480V, T_J = 125^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	—	1.7	V	$I_C = 27A, T_J = 25^\circ\text{C}$
		—	—	1.5		$I_C = 27A, T_J = 125^\circ\text{C}$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
Q_G	Total Gate Charge (turn-on)	—	—	140	nC	$I_C = 27A, V_{CC} = 300V$
Q_{GE}	Gate-Emitter Charge (turn-on)	—	—	35		See Fig. 8
Q_{GC}	Gate-Collector Charge (turn-on)	—	—	70		$V_{GE} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	—	50	ns	$I_C = 27A, V_{CC} = 480V$
t_r	Rise Time	—	—	75		$T_J = 25^\circ\text{C}$
$t_{d(off)}$	Turn-Off Delay Time	—	—	300		$V_{GE} = 15V, R_G = 2.35\Omega$
t_f	Fall Time	—	—	210		Energy losses include "tail"
E_{on}	Turn-On Switching Loss	—	0.12	—	mJ	See Fig. 10 and 15a
E_{off}	Turn-Off Switching Loss	—	1.6	—		
E_{ts}	Total Switching Loss	—	1.7	2.8		
$t_{d(on)}$	Turn-On Delay Time	—	24	—	ns	$I_C = 27A, V_{CC} = 480V$
t_r	Rise Time	—	27	—		$T_J = 125^\circ\text{C}$
$t_{d(off)}$	Turn-Off Delay Time	—	180	—		$V_{GE} = 15V, R_G = 2.35\Omega$
t_f	Fall Time	—	130	—		See Fig. 10 and 15a
E_{ts}	Total Switching Loss	—	2.7	—	mJ	
L_E	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	2900	—	pF	$V_{GE} = 0V$
C_{oes}	Output Capacitance	—	330	—		$V_{CC} = 30V$
C_{res}	Reverse Transfer Capacitance	—	41	—		$f = 1.0\text{MHz}$
t_{rr}	Diode Peak Reverse Recovery Time	—	—	100	ns	$di/dt = 200A/\mu s, I_F = 27A$
Q_{rr}	Diode Peak Reverse Recovery Charge	—	—	375	nC	$T_J = 25^\circ\text{C}, V_R \leq 200V$ $T_J = 125^\circ\text{C}, V_R \leq 200V$

Notes: ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature.
(See Fig. 13b).

② $V_{CC} = 80\% (V_{CES})$, $V_{GE} = 20V$, $L = 10\mu H$,
 $R_G = 10\Omega$. (See Fig. 13a).

③ Pulse width $\leq 5\mu s$, single shot.

Power dissipation = 47W

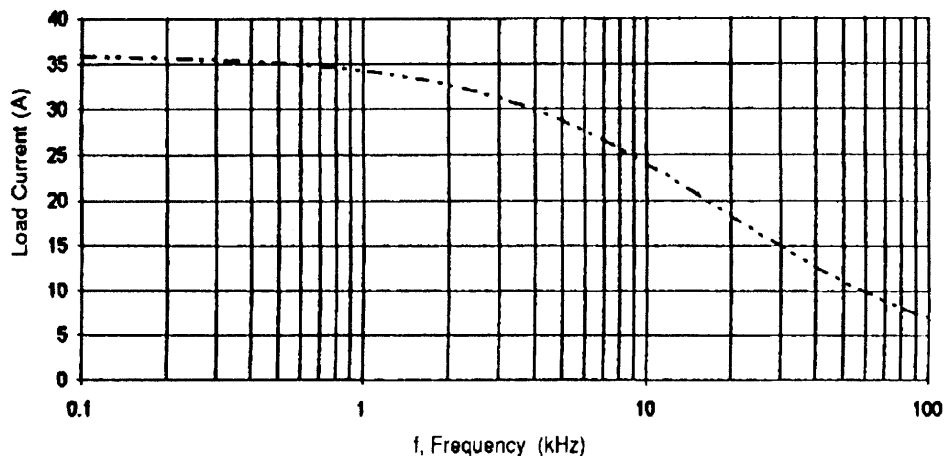


Fig. 1. Typical Load Current vs. Frequency
(For square wave, $I = I_{RMS}$ of fundamental; for triangular wave, $I = I_{PK}$)

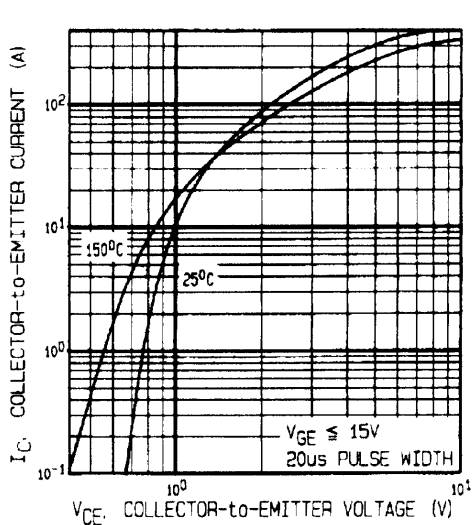


Fig. 2. Typical Output Characteristics

$T_J = 25^\circ\text{C}$
 $T_J = 150^\circ\text{C}$

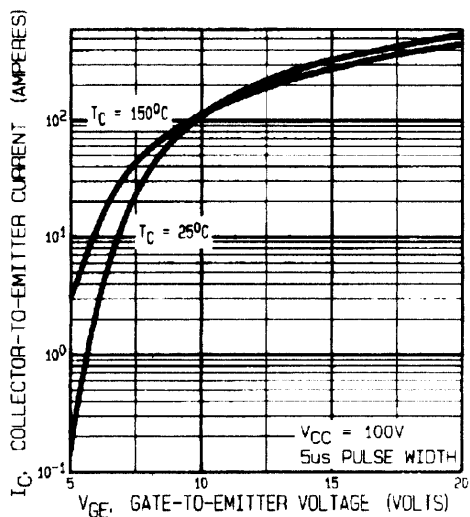


Fig. 3. Typical Transfer Characteristics

$T_J = 25^\circ\text{C}$
 $T_J = 150^\circ\text{C}$

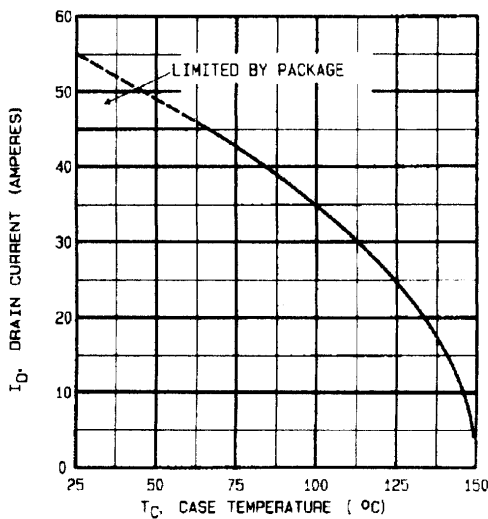


Fig. 4 Maximum Collector Current vs. Case Temperature

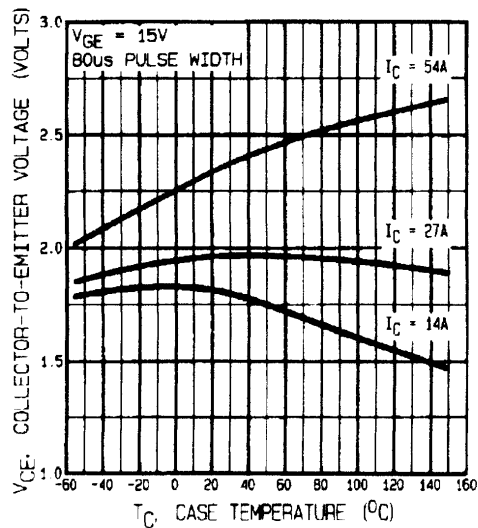


Fig. 5 Collector-to-Emitter Saturation Voltage vs. Case Temperature

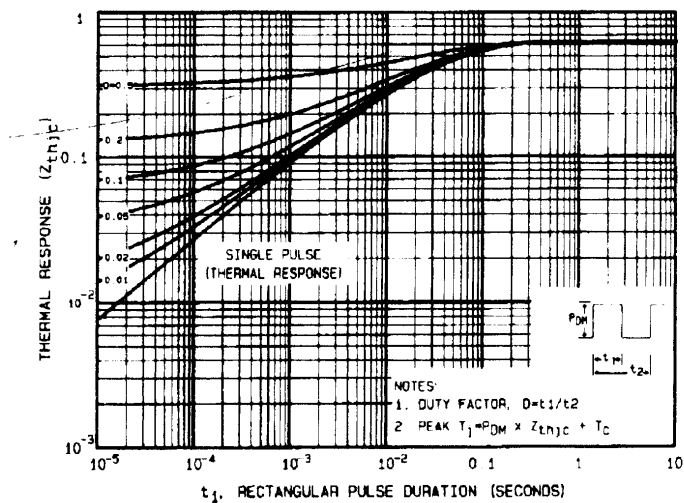


Fig. 6. Maximum Effective Transient Thermal Impedance, Junction-to-Case

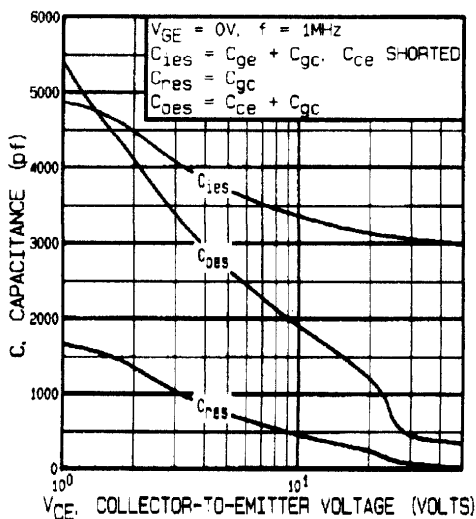


Fig. 7. Typical Capacitance vs. Collector-to-Emitter Voltage

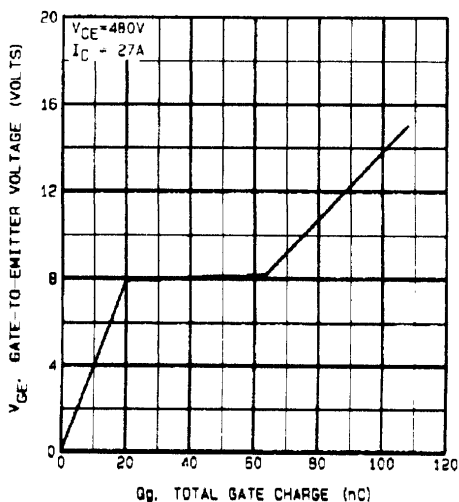


Fig. 8. Typical Gate Charge vs. Gate-to-Emitter Voltage

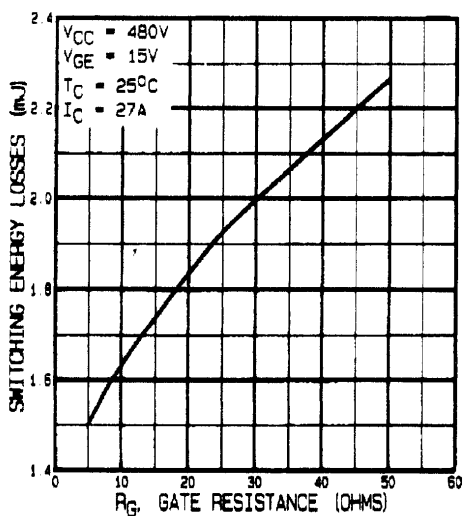


Fig. 9. Typical Switching Losses vs. Gate Resistance

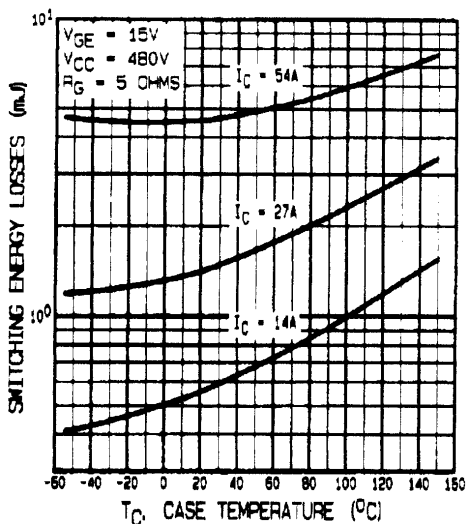


Fig. 10. Typical Switching Losses vs. Case Temperature

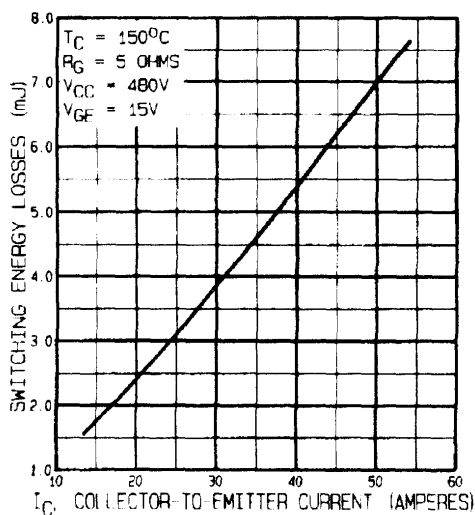
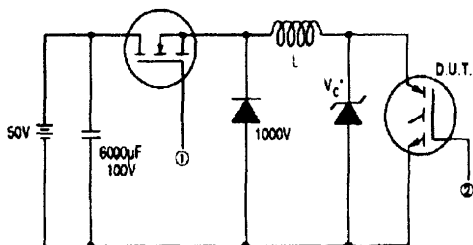


Fig. 11. Typical Switching Losses vs. Collector-to-Emitter Current



* Driver same type as D.U.T.; $V_G = 80\%$ of $V_{GS(max)}$

* Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated I_d .

Fig. 12a. Clamped Inductive Load Test Circuit

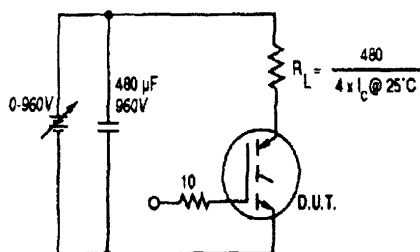


Fig. 12b. Pulsed Collector Current Test Circuit

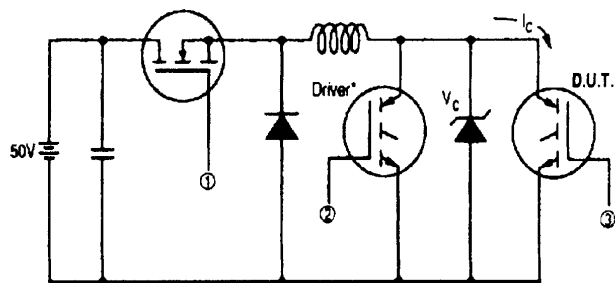


Fig 13a. Switching Loss Test Circuit

* Driver same type
as D.U.T., $V_c = 480V$

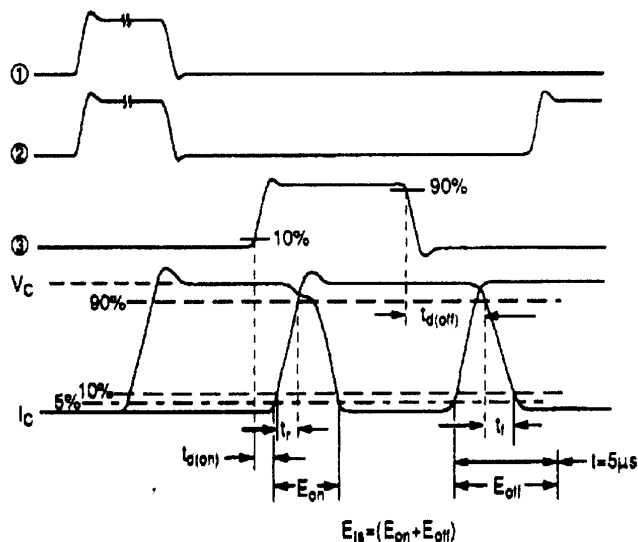


Fig 13b. Switching Loss Waveforms

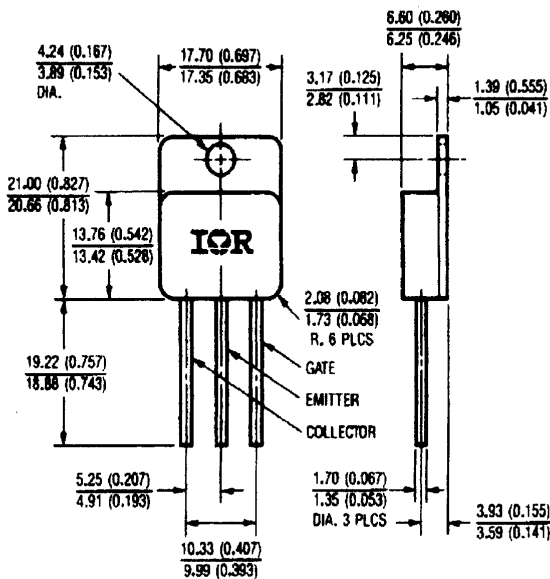
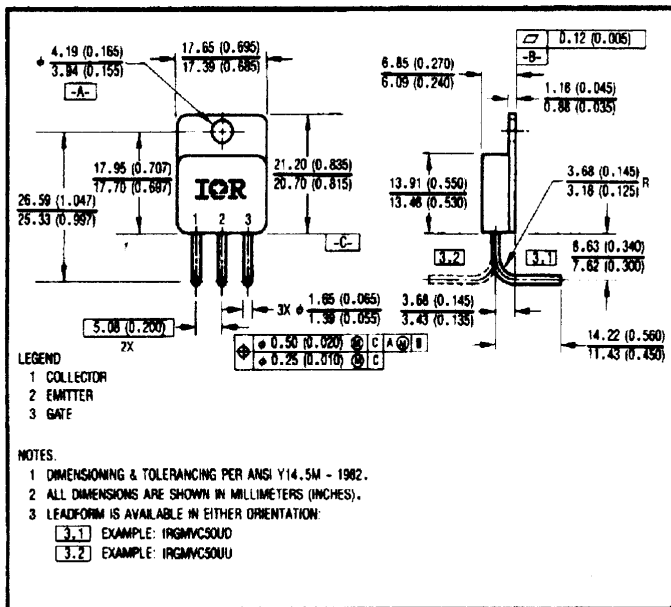


Fig. 14 – Conforms to JEDEC Outline TO-258AA
Dimensions in Millimeters and (Inches)



BERYLLIA WARNING PER MIL-S-19500
Packages containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

Fig. 15 – Optional Leadforms for Outline TO-258